











TPS60240, TPS60241, TPS60242, TPS60243

SLVS372C -JUNE 2001-REVISED OCTOBER 2015

TPS6024x 170-µVrms Zero-Ripple Switched Capacitor Buck-Boost **Converter for VCO Supply**

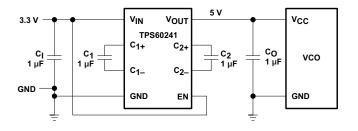
Features

- Wide Input Voltage Range from 1.8 V to 5.5 V
- Regulated 2.7-V, 3-V, 3.3-V or 5-V Output Voltage With ±2.5% Accuracy Over Load
- Up to 25-mA Output Current
- 170-µVrms Zero Ripple Output: at 20 Hz to 10 MHz Bandwidth
- Up to 90% Efficiency
- Minimum Number of External Components
 - No Inductors
 - Only Small Ceramic Chip Capacitors
- Shutdown Mode: 0.1 µA Typical
- Thermal Protection and Current Limit
- Micro-Small 8-Pin VSSOP Package
- EVM Available TPS60241EVM-194

Applications

- VCO and PLL Power for:
 - Smart Phones
 - Mobile Phones
 - **PCMCIA Modems**
- **Smartcard Readers**
- **Digital Cameras**
- MP3 Players
- SIM Modules
- **Electronic Games**
- Memory Backup
- Handheld Meters
- **Bias Supplies**

Typical Application Schematic



3 Description

The TPS6024x devices are a family of switched capacitor voltage converters, ideally suited for voltage-controlled oscillator (VCO) and phase-locked loop (PLL) applications that require low noise and tight tolerances. Its dual-cap design uses four ceramic capacitors to provide ultra-low output ripple with high efficiency, while eliminating the need for inefficient linear regulators.

The TPS6024x devices operate down to 1.8 V, supporting a 3.3-V, 2.7-V, 3-V output from two-cell, nickel- or alkaline-based chemistries, whereas the TPS60241 works with 2.7-V to 5.5-V input voltage providing a 5-V output. The devices work equally well for low EMI DC-DC step-up conversion without the need for an inductor. The high switching frequency (typical 160 kHz) promotes the use of small surfacemount capacitors, saving board space. The shutdown mode of the converter conserves battery energy.

The devices are thermally protected and currentlimited for reliable operation even under persisting fault conditions. Normal quiescent current (ground pin current) is only 250 µA, and typically 0.1 µA in shutdown mode. The TPS6024x devices come in a thin, 8-pin VSSOP package with a component height of only 1.1 mm.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	OUTPUT VOLTAGE
TPS60240		3.3 V
TPS60241	\/CCOD (0)	5 V
TPS60242	VSSOP (8)	2.7 V
TPS60243		3 V

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Efficiency vs Output Current

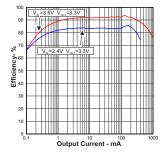




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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

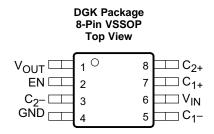
Changes from Revision B (January 2002) to Revision C

Page

- Added Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional
 Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device
 and Documentation Support section, and Mechanical, Packaging, and Orderable Information section



5 Pin Configuration and Functions



Pin Functions

PIN		1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
C ₁₊	7	_	Positive pin of the flying capacitor C ₁
C ₁₋	5	_	Negative pin of the flying capacitor C ₁
C ₂₊	8	_	Positive pin of the flying capacitor C ₂
C ₂ -	3	_	Negative pin of the flying capacitor C ₂
EN	2	I	Enable pin, active high
GND	4	_	Ground
V _{IN}	6	I	Supply voltage input TPS60241: 2.7 V to 5.5 V, TPS60240/2/3: 1.8 V to 5.5 V. Bypass V_{IN} to GND with a 1- μ F external capacitor (C_{IN}).
V _{OUT}	1	0	Regulated power output. Bypass V_{OUT} to GND with a 1- μ F external filter capacitor (C_{OUT}). TPS60241: regulated 5-V output, TPS60240: regulated 3.3-V output, TPS60242: regulated 2.7-V output, TPS60243: regulated 3-V output



6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT	
V_{DD}	Supply voltage	-0.3	6	V	
P_{D}	Power dissipation	Inte	Internally limited		
	Voltage EN	-0.3	6	V	
	Voltage C ₂₋ , C ₁₋	-0.3	V _{IN} or 5.5 ⁽²⁾	V	
	Voltage C ₂₊ , C ₁₊	-0.3	V_{IN} , V_{OUT} , or $5.5^{(2)}$	V	
T_{J}	Junction temperature		125	°C	
	Short circuit output current		80	mA	
T _{stg}	Storage temperature	-65	150	°C	

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000		
V _(ESD)	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±500	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V _{IN}	Innut voltogo	TPS60240, TPS60242, TPS60243	1.8		5.5	V
	Input voltage	TPS60241	2.7		5.5	V
I _{OUT}	Output current		25		mA	
C _{IN}	Input capacitor			1		μF
C ₁ , C ₂	Flying capacitors			1		μF
C _{OUT}	Output capacitor			1		μF
T _A	Operating temperatur	е	-40		85	°C

6.4 Thermal Information

		TPS6024x	
	THERMAL METRIC ⁽¹⁾	DGK (VSSOP)	UNIT
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	174	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	66	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	95	°C/W
ΨЈТ	Junction-to-top characterization parameter	8.8	°C/W
ΨЈВ	Junction-to-board characterization parameter	94	°C/W
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	n/a	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ Whichever is lowest.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



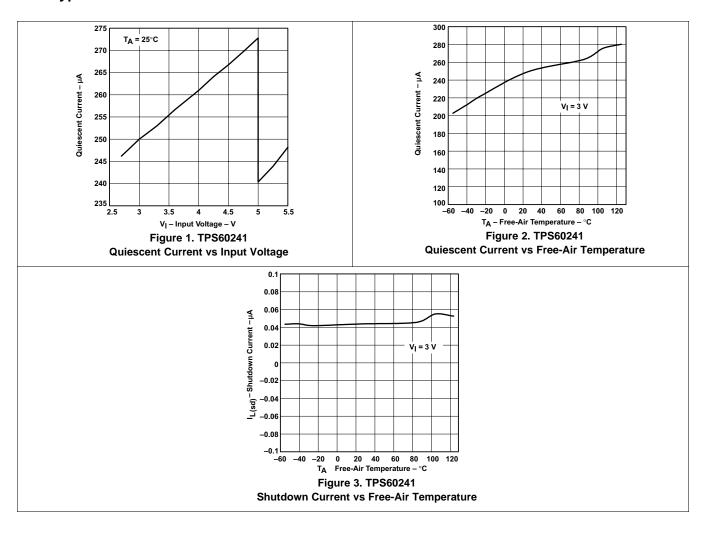
6.5 Electrical Characteristics

For TPS6024x at T_A = 25°C, C_{IN} = C_{OUT} =1 μ F, C_1 = C_2 = 1 μ F (unless otherwise noted), limits apply over the specified temperature range, -40°C to 85°C.

	PARA	METER		TEST CONDITIONS	MIN	TYP	MAX	UNIT		
		TPS60240 assu	red start-up	$I_{OUT} \le 5 \text{ mA}, R_L = 600 \Omega$	1.8		5.5			
V_{IN}	Innut valtage	TPS60241 assu	red start-up	$I_{OUT} \le 12 \text{ mA}, R_L = 417 \Omega$	2.7		5.5	V		
	Input voltage	TPS60242 assu	red start-up	$I_{OUT} \le 12 \text{ mA}, R_L = 225 \Omega$	1.8	V				
		TPS60243 assu	red start-up	$I_{OUT} \le 10 \text{ mA}, R_L = 300 \Omega$	1.8	5.5				
		TPS60240		$1.8 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 5 \text{ mA}$	3.2175	3.3	3.3825			
		12560240		2.4 V ≤ V _{IN} ≤ 5.5 V, 0 mA ≤ I _{OUT} ≤ 25 mA	3.2175	3.3	3.3825			
		TPS60241		$2.7 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 12 \text{ mA}$	4.875	5	5.125			
\/	Output valtage	17360241		$3 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 25 \text{ mA}$	4.875	5	5.125	V		
V _{OUT}	Output voltage	TPS60242		$1.8 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 12 \text{ mA}$	2.6325	2.7	2.7675	V		
		17300242		$2.3 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 25 \text{ mA}$	2.6325	2.7	2.7675			
		TPS60243		$1.8 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 10 \text{ mA}$	2.925	3	3.075			
		1F360243		$2.3 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, 0 \text{ mA} \le \text{I}_{\text{OUT}} \le 25 \text{ mA}$	2.925	3	3.075			
		TDS60240/2/2	Nominal	$2 \text{ V} \leq \text{V}_{IN} \leq 5.5 \text{ V}$	12					
	Output aurent	17360240/2/3	PS60240/2/3 Short circuit V _{IN} = 2 V				80			
I _{OUT}	Output current	TPS60241	TDS60244	Nominal	2.7 V ≤ V _{IN} ≤ 5.5 V	12			mA	
		17560241	Short circuit	V _{IN} = 3.25 V	8		80			
f_{OSC}	Internal clock source	•	•		100	160	300	kHz		
	Output a size wells as	TPS60240/2/3		V_{IN} < 2.5 V, I_{OUT} = 5 mA, ESR < 0.1 Ω, Measured over 20 Hz to 10 MHz, C_{OUT} = 4.7 μF		170)/ DMC		
V _n	Output noise voltage	TPS60241		V_{IN} = 2.7 V, I_{OUT} = 5 mA, ESR < 0.1 Ω, Measured over 20 Hz to 10 MHz, C_{OUT} = 4.7 μF		170		μV RMS		
V _{IH}	Logic high input voltag	e, EN			1.3		5.5	V		
V _{IL}	Logic low input voltage	e, EN			-0.2		0.4	V		
I _{IH}	Logic high input currer	nt, EN					100	nA		
I _{IL}	Logic low input current	, EN					100	nA		
t _(EN)	Start-up time, EN			V_{OUT} > 90% of $V_{(NOM)},~0.1~\text{mA} \leq I_{OUT} \leq 10~\text{mA},~C_{OUT}$ = $1~\mu\text{F}$		0.5		ms		
		TPS60240		I _{OUT} = 5 mA, V _{IN} = 1.8 V		89.6%				
_	Γ α :-!	TPS60241		I _{OUT} = 10 mA, V _{IN} = 2.7 V		90.8%				
η	Efficiency	TPS60242		I _{OUT} = 10 mA, V _{IN} = 1.8 V		73%				
		TPS60243		I _{OUT} = 10 mA, V _{IN} = 1.8 V		81%				
	0	•		I _{OUT} = 0 mA, V _{IN} = 3 V		250	400			
IQ	Quiescent current			In shutdown mode	0.1 1			μΑ		
	The annual about days	Temperature ac	tivated			160		00		
	Thermal shutdown	Temperature de	activated			140		°C		



6.6 Typical Characteristics





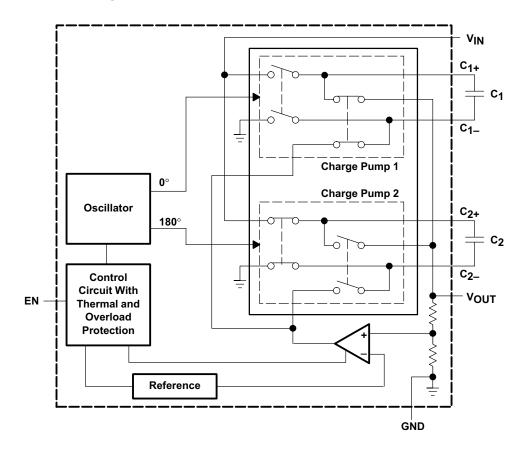
7 Detailed Description

7.1 Overview

The TPS6024x device is a fixed-frequency, dual-phase charge pump that provides 25 mA of continuous supply current for low-noise applications such as VCOs used in mobile phones and wireless applications.

Low-noise operation results from using a proprietary dual-phase charge pump topology that relies on an operational amplifier in the feedback loop to reduce ripple. During the first phase, C_1 is charged to the supply voltage. Pin C_{1+} is connected to V_{IN} , and C_{1-} is connected to GND. In the second phase, C_{1-} is connected to the output of the operational amplifier, and C_{1+} is connected to V_{OUT} . The operational amplifier then adjusts its output until the output V_{OUT} delivers the correct voltage to make the resistor divided feedback point equal to the reference voltage. During this second phase, C_2 is charged to supply voltage. Terminal C_{2-} is connected to GND, and C_{2+} is connected to V_{IN} . Phase one is then repeated with C_2 , now acting to provide charge to the output in place of C_1 , which is connected to the supply. The dual-phase operation lowers the output ripple voltage significantly compared to a standard single-phase charge pump. In addition, the linear feedback of the operational amplifier eliminates the ripple during discharge of the output capacitor (C_{OUT}).

7.2 Functional Block Diagram





7.3 Feature Description

7.3.1 Thermal Shutdown

The TPS6024x device has a built-in thermal shutdown which turns off the power stage when the junction temperature exceeds typical 160°C. When the junction temperature drops to typical 140°C, the device starts switching again.

7.3.2 Current Limit

The TPS6024x device has a built-in overload protection which limits the output current.

7.4 Device Functional Modes

7.4.1 Start-up Procedure

The converter is enabled when EN is set from logic low to high. The start-up time to reach 90% of the nominal output voltage is typically 0.5 ms at load currents lower than 10 mA and with an output capacitor of 1 μ F. Increasing the values of C_{OUT} delays the start-up time.

7.4.2 Shutdown

Driving EN low disables the converter. This disables the internal circuits and reduces input current to typically 0.1 μ A. In this mode, the load is disconnected from the supply voltage. The device exits shutdown once EN is set to a high level.



8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TPS6024x is a switched capacitor voltage converter for VCO and PLL applications providing low noise conversion and tight tolerances. It supports regulated output voltages of 2.7 V, 3 V and 3.3 V from a 1.8-V to 5.5-V input voltage range. The TPS60241 generates 5-V output voltage from an 2.7-V to 5.5-V input voltage range.

8.2 Typical Applications

8.2.1 5-V Low-Noise VCO Supply from 3.3-V Input

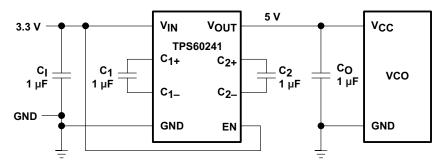


Figure 4. 5-V Low-Noise VCO Supply from 3.3-V Input

8.2.1.1 Design Requirements

The complete charge pump circuitry requires no inductors and only four small ceramic capacitors.

8.2.1.2 Detailed Design Procedure

8.2.1.2.1 Output Voltage Ripple

The output voltage ripple depends on the capacitors used. Table 1 shows the dependence between output voltage ripple and capacitor selection.

Table 1. Output Voltage Ripple and Capacitor Selection⁽¹⁾

Ci	Co	C ₁	C ₂	OUTPUT VOLTAGE RIPPLE [µVrms]
1 μF	1 μF	1 μF	1 μF	288
2.2 µF	2.2 µF	1 μF	1 μF	212
4.7 μF	4.7 µF	1 μF	1 μF	183
4.7 µF	1 µF	1 µF	1 µF	272
1 μF	4.7 µF	1 μF	1 μF	185

(1) NOTE: V_{IN} = 3.3 V, V_{OUT} = 5 V, R_L = 500 Ω , T_A = 25°C

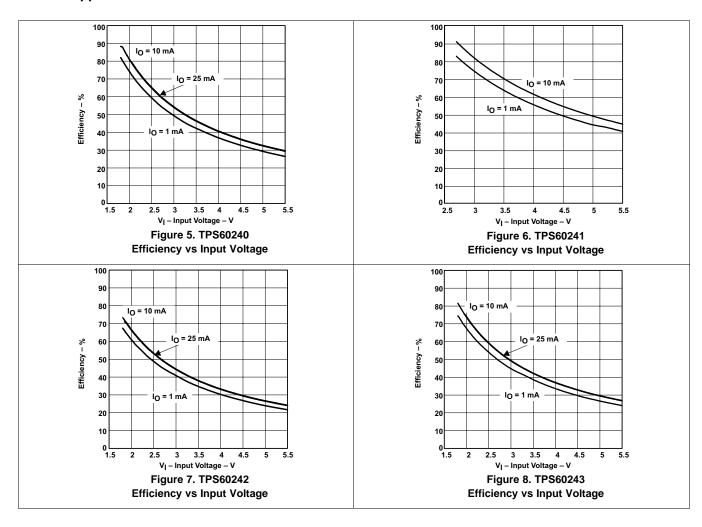


For the best output ripple performance, low-ESR ceramic capacitors are recommended (see Table 2).

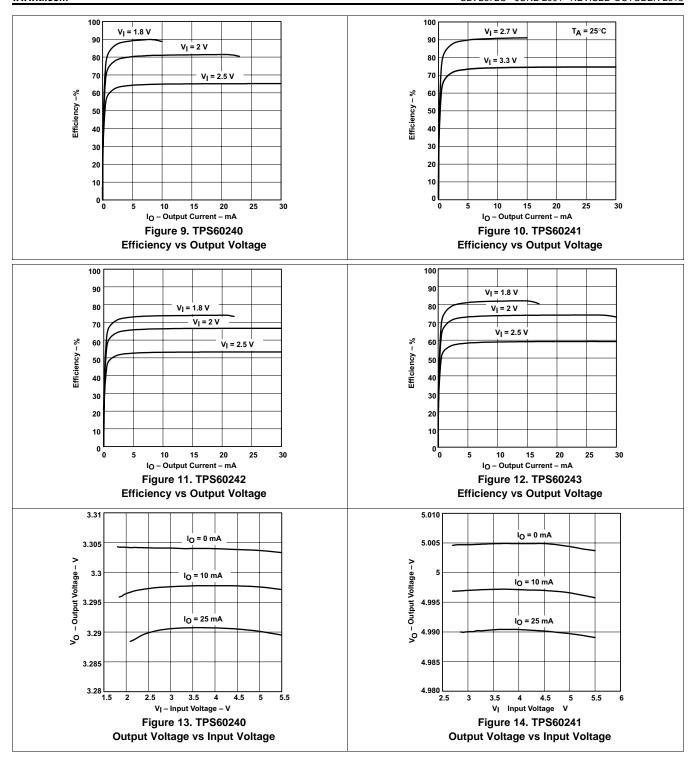
Table 2. Recommended Capacitors

PART	MANUFACTURER	PART NUMBER	VALUE	TOLERANC E	DIELECTRIC MATERIAL	PACKAGE	RATED VOLTAGE
CI	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
	TDK	C2012X5R0J475K	4.7 μF	10%	X5R	0805	6.3
CO	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
	TDK	C2012X5R0J475K	4.7 µF	10%	X5R	0805	6.3
C1, C2	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10
CF	Taiyo Yuden	LMK212BJ105KG-T	1 μF	10%	X7R	0805	10

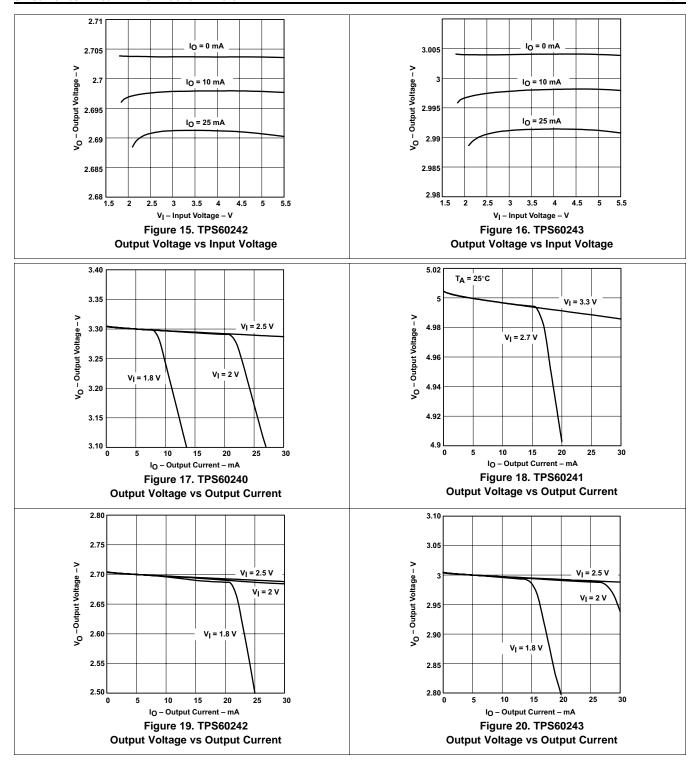
8.2.1.3 Application Curves



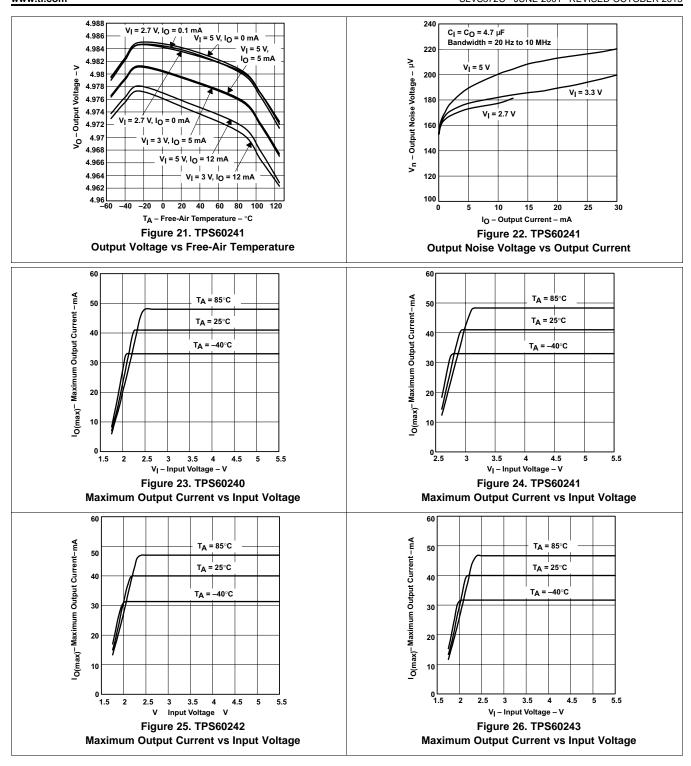




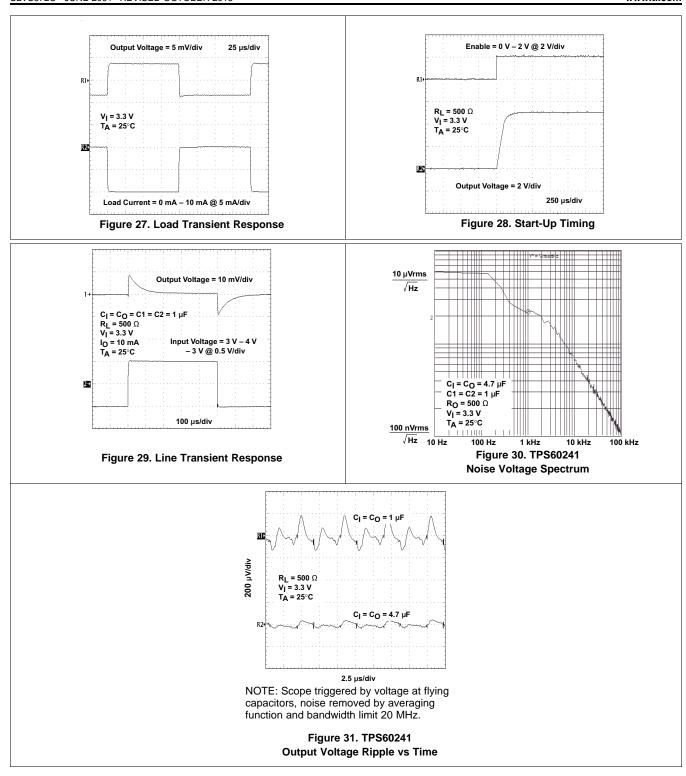














8.2.2 2-V to 3.3-V Low-Noise Converter

Standard application as a low noise boost converter. The device generates a regulated output voltage of 3.3 V from a 2-V supply with only 4 external 1-µF ceramic capacitors.

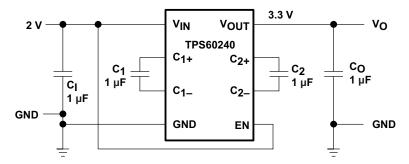


Figure 32. 2-V to 3.3-V Low-Noise Converter



9 Power Supply Recommendations

The TPS6024x devices have no special requirements for the input power supply. The output current of the input power supply must be rated according to the supply voltage, output voltage, and output current of the TPS6024x.

10 Layout

10.1 Layout Guidelines

To achieve optimal noise behavior, keep the power lines to the capacitors and load as short as possible. Use of power planes is recommended.

10.2 Layout Examples

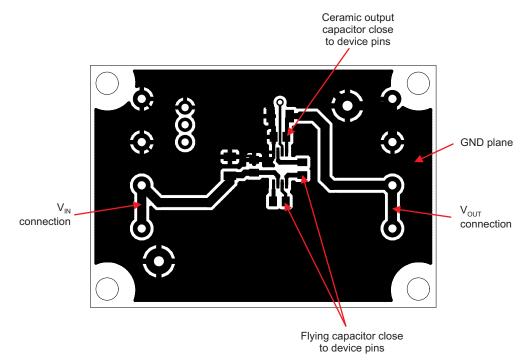


Figure 33. Top Layer

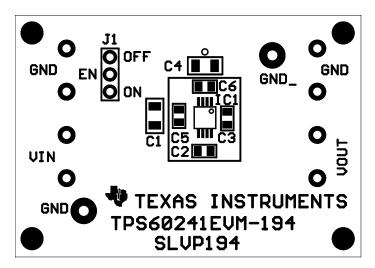


Figure 34. Top Silkscreen



11 Device and Documentation Support

11.1 Device Support

11.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

11.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 3. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TPS60240	Click here	Click here	Click here	Click here	Click here
TPS60241	Click here	Click here	Click here	Click here	Click here
TPS60242	Click here	Click here	Click here	Click here	Click here
TPS60243	Click here	Click here	Click here	Click here	Click here

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community T's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





24-Aug-2018

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
TPS60240DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60241DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60242DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYF	Samples
TPS60243DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

24-Aug-2018

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	VSSOP	DGK	8	250	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
TPS60240DGKR	VSSOP	DGK	8	2500	366.0	364.0	50.0	
TPS60240DGKT	VSSOP	DGK	8	250	366.0	364.0	50.0	
TPS60241DGKR	VSSOP	DGK	8	2500	366.0	364.0	50.0	
TPS60241DGKT	VSSOP	DGK	8	250	366.0	364.0	50.0	
TPS60242DGKT	VSSOP	DGK	8	250	366.0	364.0	50.0	
TPS60243DGKR	VSSOP	DGK	8	2500	366.0	364.0	50.0	
TPS60243DGKT	VSSOP	DGK	8	250	366.0	364.0	50.0	

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